

IN THE CLAIMS:

1. (currently amended) An assembly comprising  
a substrate,

an integrated circuit device adapted to be electrically and  
mechanically attached to the substrate and having a bottom  
surface and a side surface,

electrically conductive connecting elements between the  
device and the substrate that electrically connect the device and  
the substrate, and

at least one adhesive body positioned between the integrated  
circuit device and the substrate to form a mechanical connection  
between the circuit device and the substrate, the at least one  
adhesive body being in contact with said bottom surface and said  
side surface of the integrated circuit device,

said at least one adhesive body comprising a non-  
thermosetting material which, when heated, releases said  
mechanical connection to allow removal of the circuit device from  
the substrate.

2. (original) The assembly as set forth in claim 1 wherein  
said non-thermosetting material comprises a thermoplastic  
polymer.

3. (original) The assembly as set forth in claim 2 wherein  
said thermoplastic polymer has a bonding temperature of at least  
about 100 degrees Celsius.

4. (original) The assembly as set forth in claim 2 wherein  
said thermoplastic polymer has a bonding temperature of less than  
about 300 degrees Celsius.

5. (original) The assembly as set forth in claim 1 wherein said at least one adhesive body is positioned at a peripheral edge of the integrated circuit device.

6. (original) The assembly as set forth in claim 5 wherein said circuit device has corners and the adhesive bodies are located at said corners.

7. (original) The assembly as set forth in claim 1 wherein said at least one adhesive body has a substantially spherical shape.

8. (original) The assembly as set forth in claim 1 wherein said at least one adhesive body comprises four adhesive bodies.

9. (original) The assembly as set forth in claim 1 wherein said integrated circuit device is a chip package.

10. (original) The assembly as set forth in claim 1 wherein said integrated circuit device is a multi-chip module.

11. (currently amended) The assembly as set forth in claim 1 wherein said ~~integrated circuit device has~~ a bottom surface ~~with~~ has four corners and said at least one adhesive body is located approximately equidistant from adjacent corners in contact with the bottom surface of the circuit device.

12. (currently amended) An assembly comprising  
a substrate,

an integrated circuit device adapted to be electrically and mechanically attached to the substrate and having a bottom surface and a side surface,

electrically conductive connecting elements between the device and the substrate that electrically connect the device and the substrate, and

10 at least two adhesive bodies comprising a non-thermosetting material positioned between the integrated circuit device and the substrate to form a releasable ~~mechanical~~ connection between the circuit device and the substrate, the at least two adhesive bodies being in contact with said bottom surface and said side surface of the integrated circuit device.

13. (currently amended) The assembly as set forth in claim 12 wherein said releasable ~~mechanical~~ connection is released by heating said adhesive bodies.

14. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies are spaced apart to form an open space between the adhesive bodies.

15. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies are positioned at a periphery of the integrated circuit device.

16. (original) The assembly as set forth in claim 12 wherein said integrated circuit device has corners and the at least two adhesive bodies comprise four adhesive bodies positioned at said corners.

17. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies comprise a thermoplastic polymer.

Claims 18-24. (Cancelled)

25. (New) The assembly set forth in claim 1 wherein the bottom surface of the integrated circuit device is spaced apart from the substrate by a distance and the at least one adhesive body comprises a spherical body having a diameter greater than the distance between the bottom surface of the integrated circuit device and the substrate.

26. (New) The assembly set forth in claim 25 wherein said spherical body has a diameter approximately 1.5 times the distance between the bottom surface of the integrated circuit device and the substrate.

27. (New) The assembly set forth in claim 12 wherein the bottom surface of the integrated circuit device is spaced apart from the substrate by a distance and the at least two adhesive bodies comprises a spherical body having a diameter greater than the distance between the bottom surface of the integrated circuit device and the substrate.

28. (New) The assembly set forth in claim 27 wherein said spherical body has a diameter approximately 1.5 times the distance between the bottom surface of the integrated circuit device and the substrate.

29. (New) An assembly comprising  
a substrate,

an integrated circuit device adapted to be electrically and mechanically attached to the substrate and having a bottom surface and a side surface, the bottom surface being spaced apart from the substrate by a distance,

electrically conductive connecting elements between the device and the substrate that electrically connect the device and the substrate, and

at least one adhesive body positioned between the integrated circuit device and the substrate to form a mechanical connection between the circuit device and the substrate, the at least one adhesive body comprising a spherical body in contact with said bottom surface and said side surface of the integrated circuit device and having a diameter greater than the distance between the bottom surface of the integrated circuit device and the substrate,

said at least one adhesive body comprising a non-thermosetting material which, when heated, releases said mechanical connection to allow removal of the circuit device from the substrate.

30. (New) The assembly set forth in claim 29 wherein said spherical body has a diameter approximately 1.5 times the distance between the bottom surface of the integrated circuit device and the substrate.